

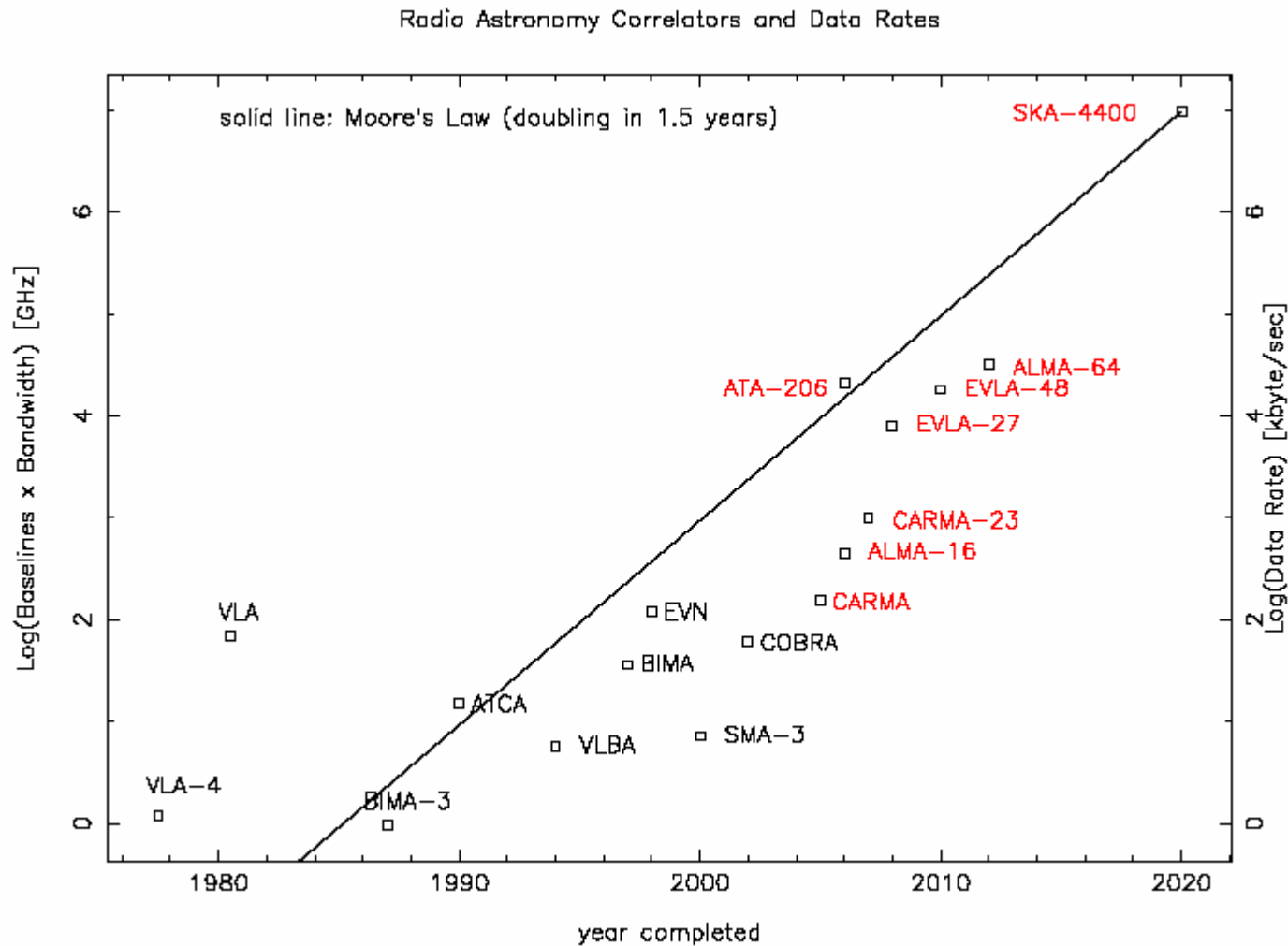


# **BEE2: a multi-purpose computing platform for radio telescope DSP applications**

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# Radio Astronomy Correlators





# Polarization, Mosaicing, and time multiplexing

- Polarization required for many astrophysical situations
- Single polarization requires time multiplexing
- Polarizer is frequency and polarization dependent
- Polarization observations are inefficient and difficult to schedule
- Mosaicing requires time multiplexing
- Polarization, mosaicing, and multiple spectral lines require multiple tracks
- Calibration of dual polarization is more robust
- Dual polarization improves sensitivity for spectral lines



# Relative performance of CARMA

Telescope	CARMA-15	CARMA-23	SMA	ALMA	ACA	IRAM PdB
nants	6x10.4 + 9x6.1	+ 8x3.5	8x6.1	64x12	4x12 + 12x7	6x15
collecting area [m <sup>2</sup> ]	773	850	230	7238	914	1060
average diameter [m]	8.1	6.9	6.1	12	8.5	15
nants x diameter	122	158	49	768	136	90
number of baselines	105	253	28	2016	120	15
max baseline/antdiam	328	571	82	375	8	58
polarizations	1	2	2	2	2	2
continuum BW /pol [GHz]	4	8	2	8	8	4
spectral windows /pol	8	8	6x4	8	8	8
window bandwidths [MHz]	2-500	2-500	82	31-2000	31-2000	20-320
spectral channels/window	64	64	64-2048	2048	8192	64-512
total spectral channels/pol	512	512	3072x2	16384	65536	4096

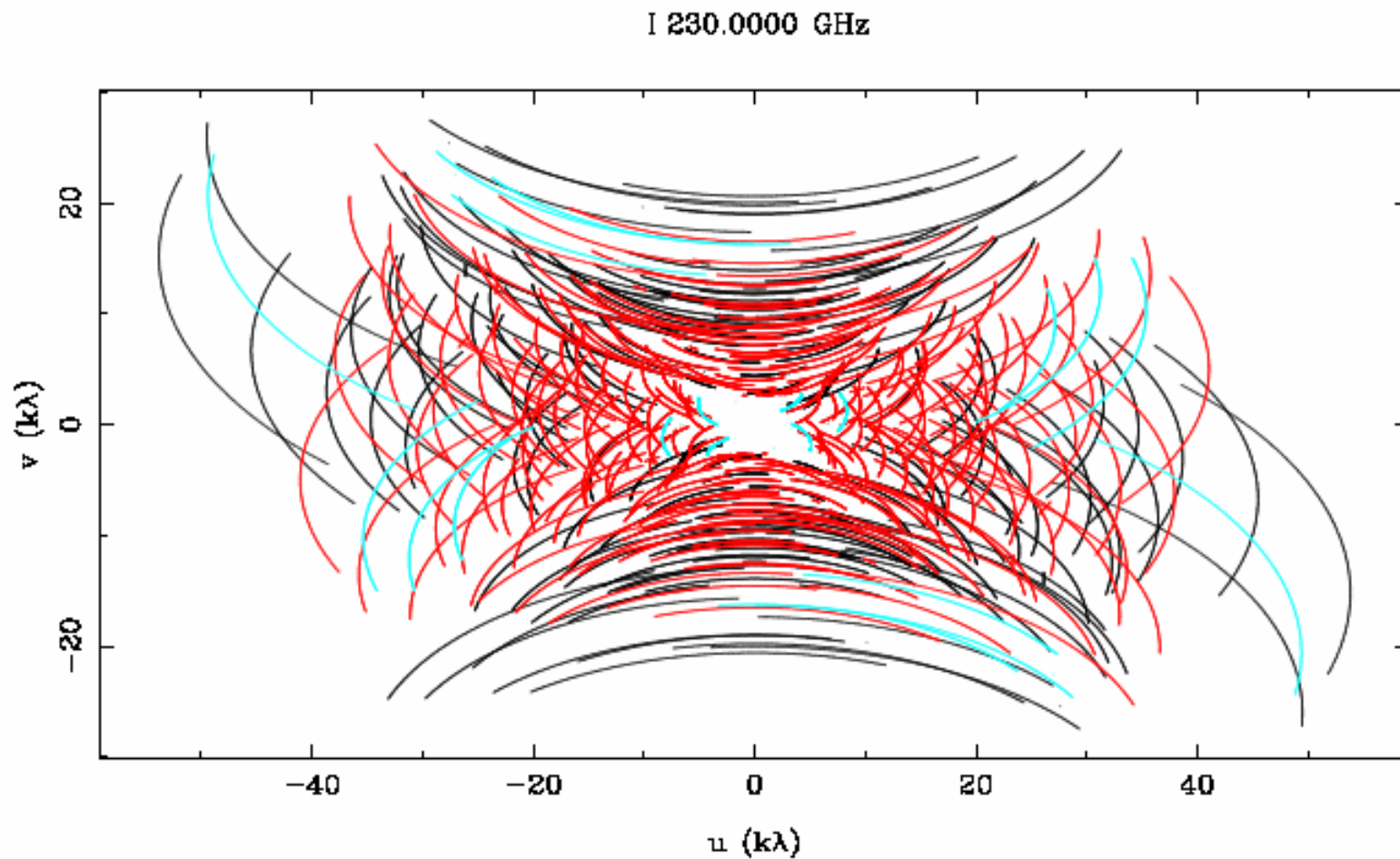


# CARMA's role

- Wide range of spatial scales
  - Heterogeneous array of 10.4, 6.1 and 3.5 m antennas
  - Antenna spacings from 4m to 2km
- Spatial frequencies sampled by interferometer
- Multiple primary beams decouple source from primary beam illumination
- Calibration of single dish and heterogeneous array from overlap in spatial frequencies
- Excellent UV coverage using CARMA and SZA

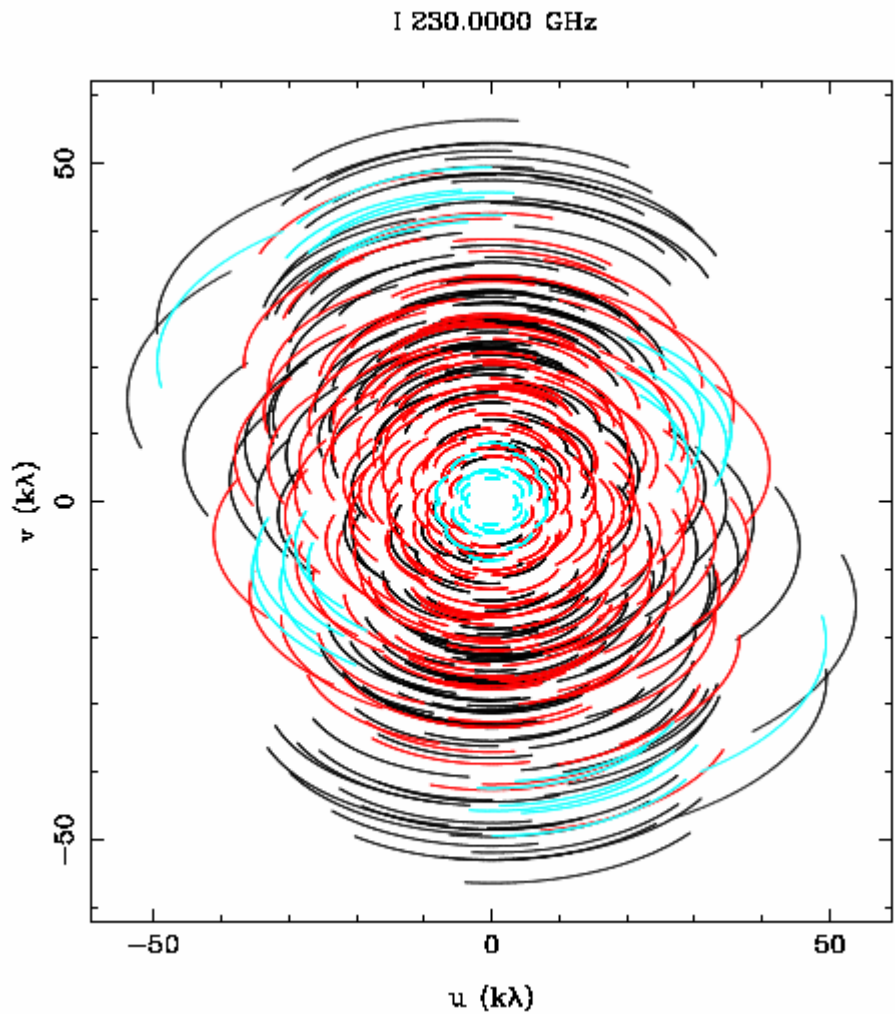


# CARMA-23 UV coverage dec=-30



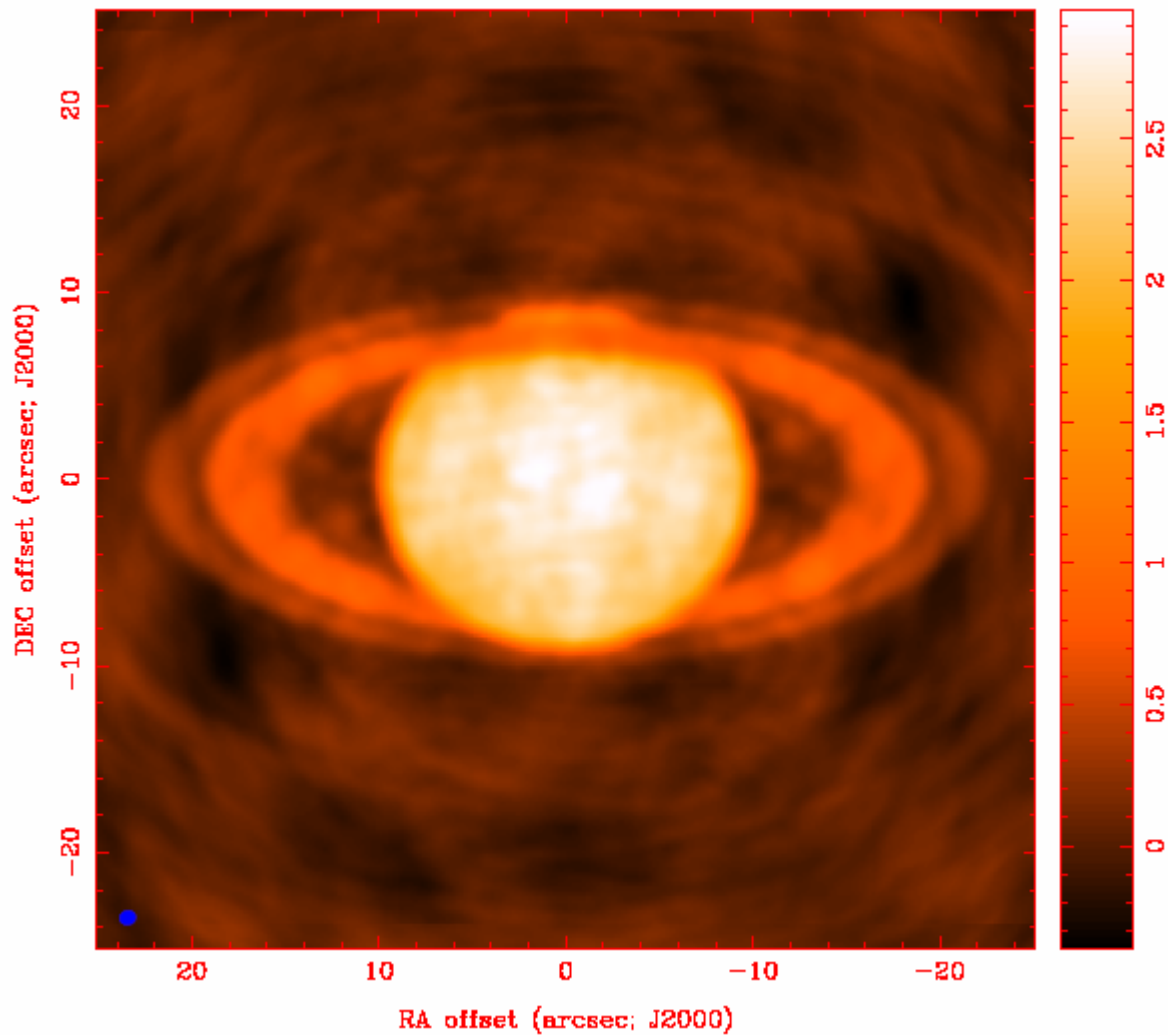


# CARMA-23 UV coverage dec=+30





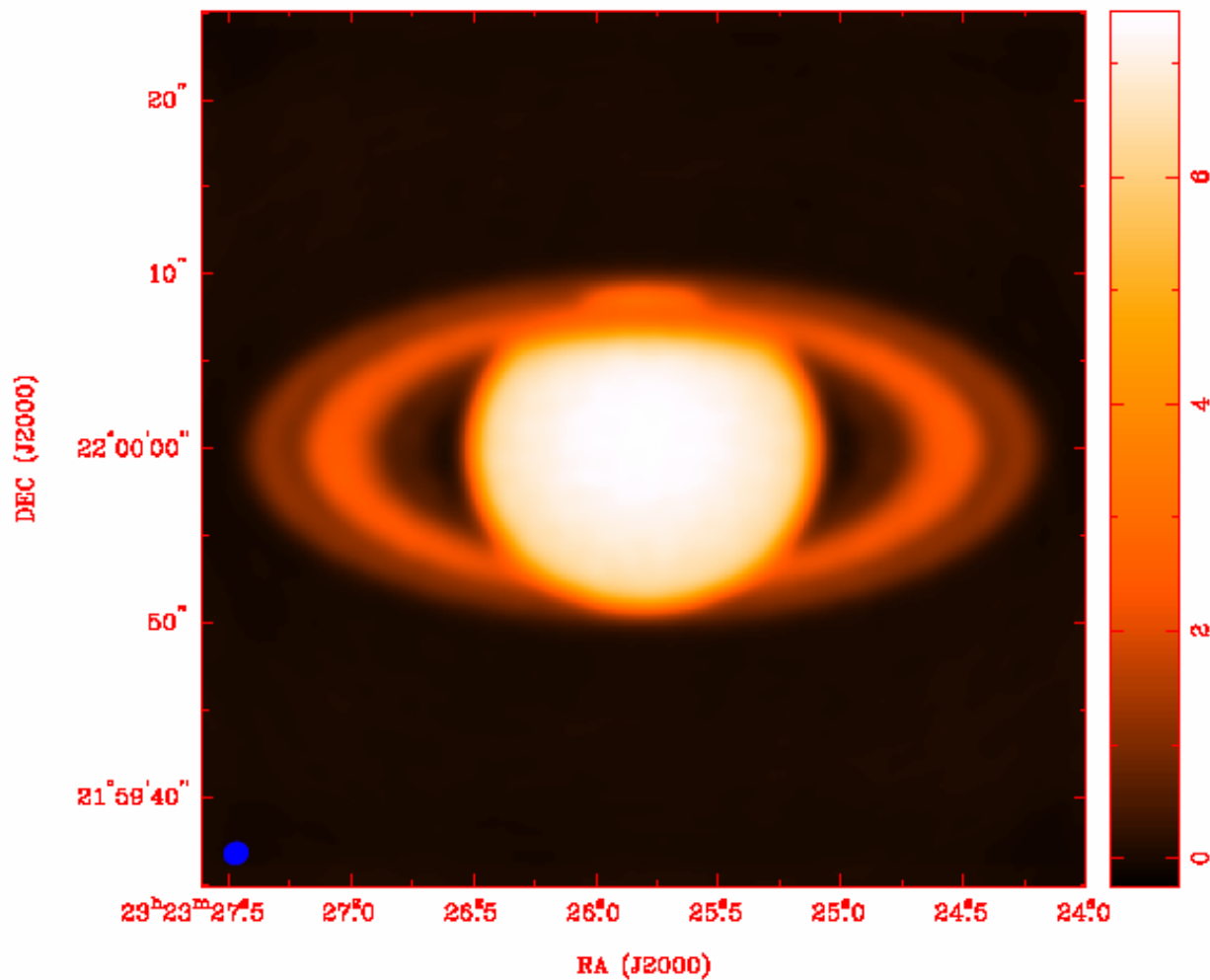
# CZ without 3.5~6.1m spacings





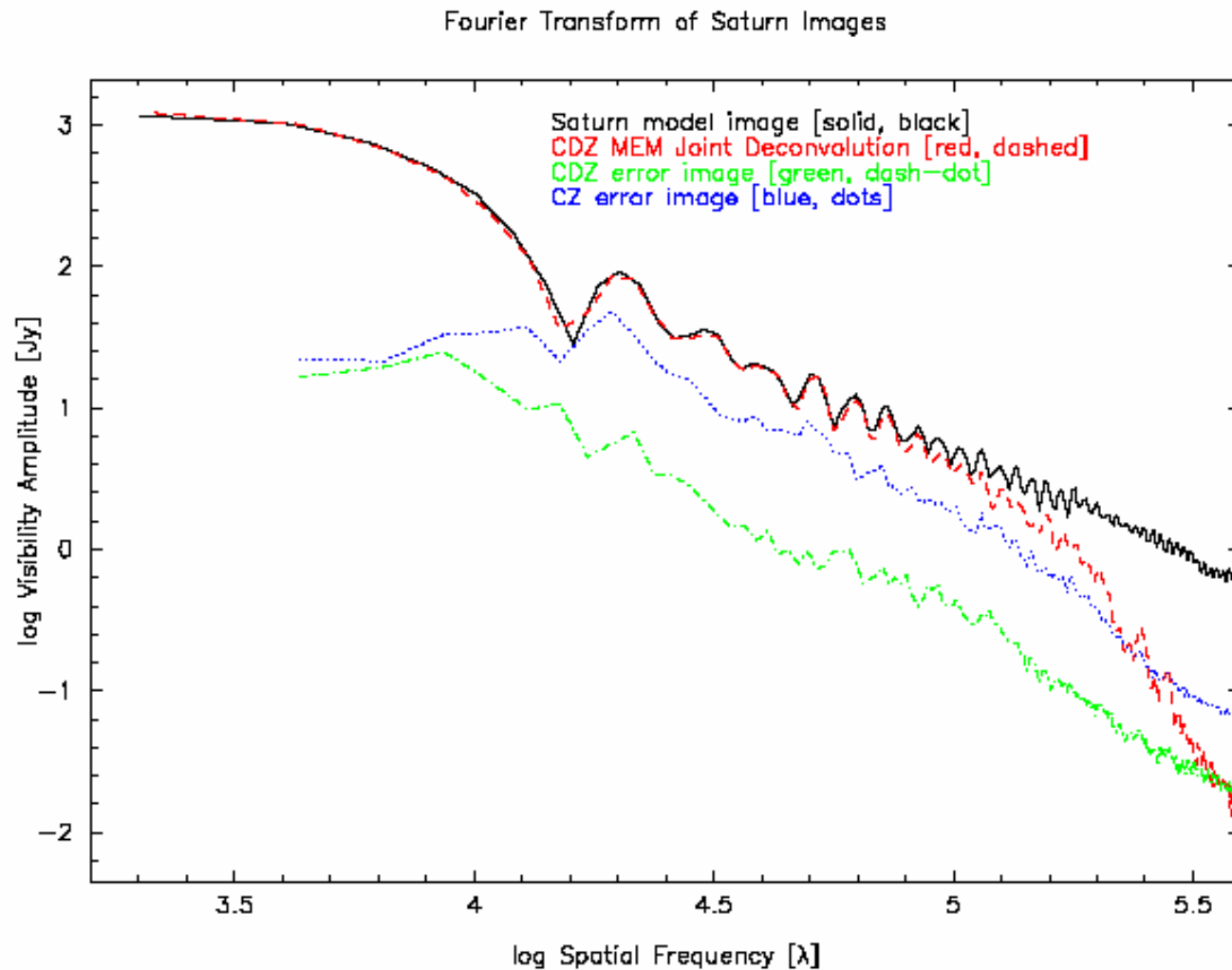


# CZ + DZ including 3.5~6.1m spacings





# Fourier Transform of Saturn Images





# CARMA as R&D array

- Accessible to instrumentalists and students
- Facilitate adding user instruments and software
- General purpose DSP backend provides access to a wider range of users, by lowering the barrier of entry
  - Pulsar processing
  - RFI mitigation
  - Beamforming



# Berkeley Wireless Research Center

- A partnership of UC Berkeley researchers, industry, and government
- 15 Industrial Members:
  - Atmel Corporation
  - Cadence Design Systems
  - Conexant Systems
  - Ericsson Radio Systems
  - Hewlett Packard Company
  - Hitachi Ltd.
  - Infineon Technologies
  - Intel Corporation
  - NEC Corporation
  - Philips Research
  - Qualcomm Incorporated
  - Samsung Electronics
  - STMicroelectronics
  - Sun Microsystems
  - Xilinx Incorporated
- Other Funding:
  - DARPA, AFRL, NSF, ONR, MARCO, MURI, CA Energy Com.
- Operational since Feb.1999
- 12000 sq. feet facility located downtown Berkeley, CA
- 60 UCB EECS Graduate Students, 11 Faculty

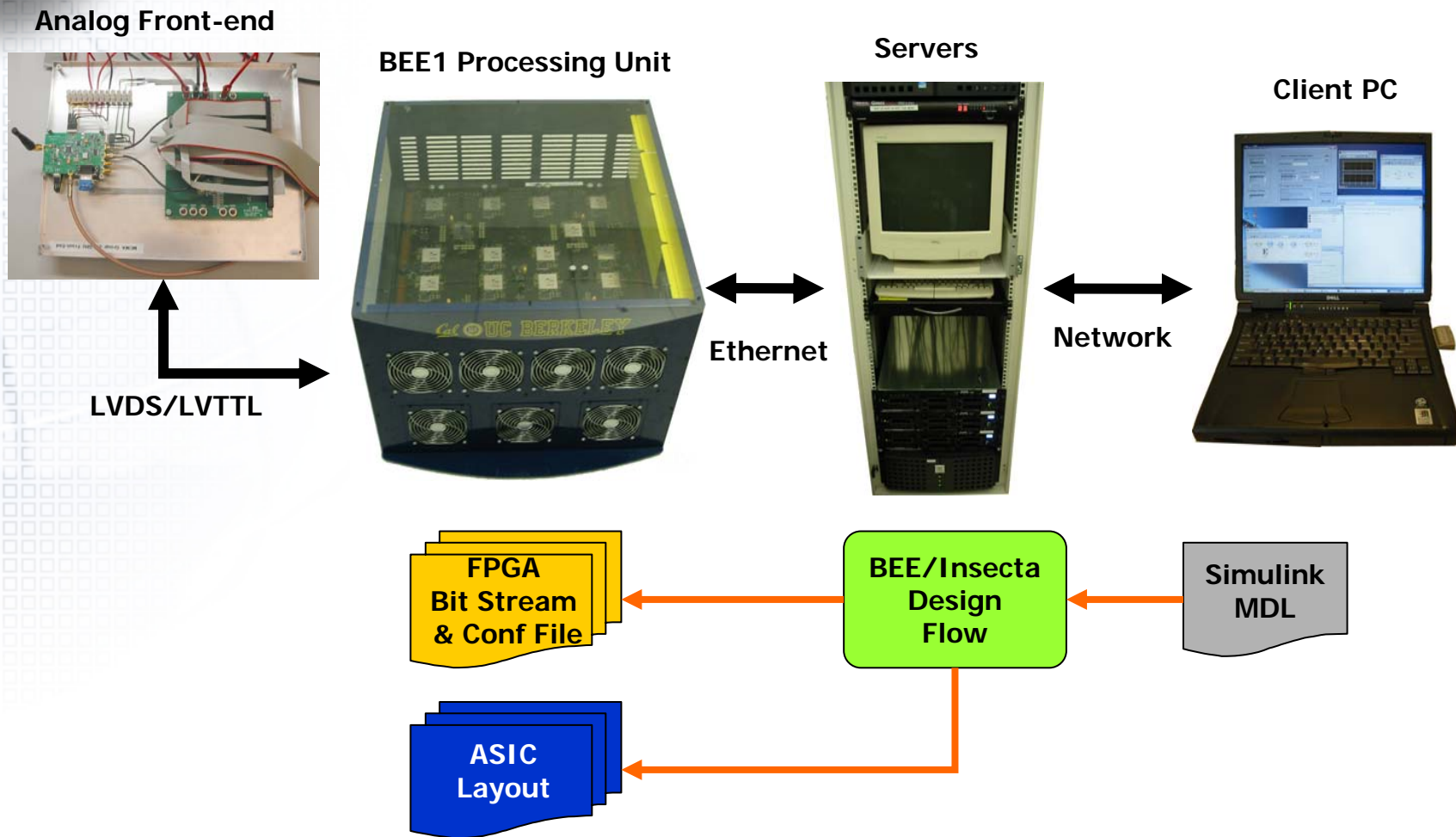


Dec 12, 2004

UC Berkeley



# BEE1 System Overview





# BEE1 system development time

- system conception & specification: 2 FTE month
- PCB design (schematics/layout): 12 FTE month
- PCB fabrication
- Hardware system testing and characterization: 2 FTE month
- Software system development (CAD tools, User Interface, Linux OS): 12 FTE month



# BEE1 application development time

- 1 Mbps QPSK Transceiver: 1 FTE month
- BCJR decoder: 3 FTE month
- IDCT MPEG encoder: 4 FTE month
- 4X4 SVD block: 6 FTE month



# BEE2 system design philosophy

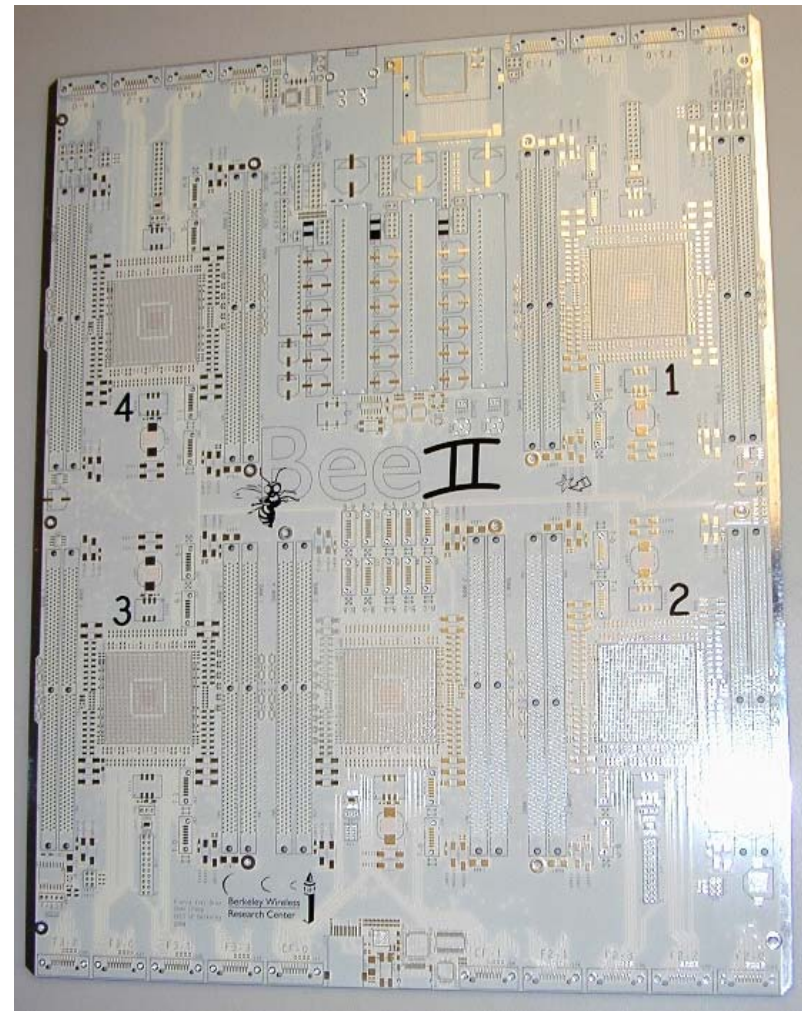
- Compute-by-the-yard
  - Modular computing resource
  - Flexible interconnect architecture
  - On-demand reconfiguration of computing resources
- Economy-of-scale
  - Ride the semiconductor industry Moore's Law curve
  - All COTS components, no specialized hardware
  - Survival of application software using technology independent design flow





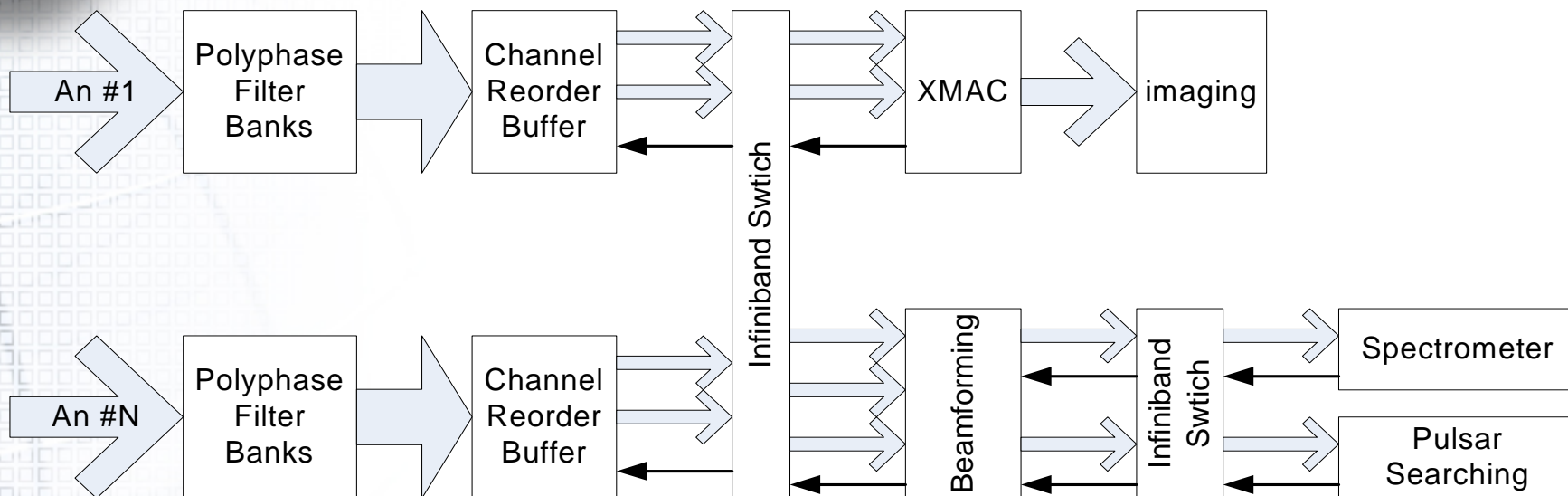
# BEE2 Module: PCB board

- Over 250 billion CMAC/s
- Up to 12.8 GBps memory bandwidth, with maximum 8 GB capacity
- 360 Gbps I/O bandwidth in 18 Infiniband 4X connectors
- 14X17 inch 22 layer PCB (FR4, 4/4 mils)





# Unified Digital Processing Architecture

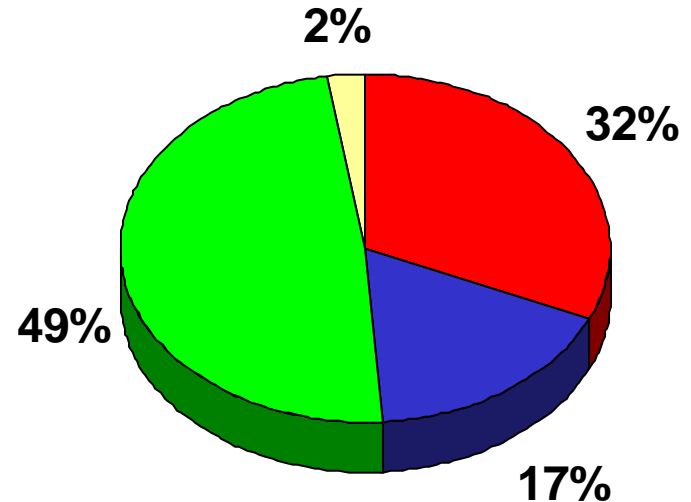


- Distributed per antenna spectral channel processing
- Multiple reconfigurable backend application processing
- Commercial packet switched interconnect
- Backend data pulling through remote DMA access
- Locally synchronous, global asynchronous



# BEE2 subsystem hardware cost

- BEE2 module: ~\$20K
  - PCB: \$6.5K
  - DDR2 Memory: \$3.5K
  - FPGA: \$10K
  - Mechanical, etc: \$0.5K
- Infiniband switch
  - 24-port IB: \$8K
  - 96-port IB: \$60K
  - 2 meter cable: \$107
  - 12 meter cable: \$333





# BEE2 correlator hardware cost table

Name	COBRA	CARMA First Light (15,1.5,1,96)	CARMA (15,4,1,128)	CARMA (15,4,1,256)	CARMA (15,4,1,512)	CARMA (23,4,2,256)	CARMA (23,4,2,512)
Antenna	6	15	15	15	15	23	23
Bandwidth	4	1.5	4	4	4	4	4
Polarization	1	1	1	1	1	2	2
Baselines	15	105	105	105	105	253	253
PFB ch/IF band	32	96	128	256	512	256	512
IF bands	8	3	8	8	8	8	8
FPGA (PFB)	1	2	4	8	15	23	46
FPGA (XMAC)	3	7	17	17	17	81	81
BEE2 (PFB)	1	1	1	2	4	6	12
BEE2 (XMAC)	1	2	5	5	5	21	21
Digitizer boards	24	22.5	60	60	60	184	184
IB cables	62	77	196	204	218	738	784
IB switches	1	2	4	4	5	16	18
\$ PFB (K)	20	20	20	40	80	120	240
\$ XMAC (K)	20	40	100	100	100	420	420
\$ cables (K)	6	8	20	20	22	74	78
\$ switch (K)	8	16	32	32	40	128	144
\$ digitizer (K)	120	68	180	180	180	552	552
\$ total(K)	174	151	352	372	422	1,294	1,434



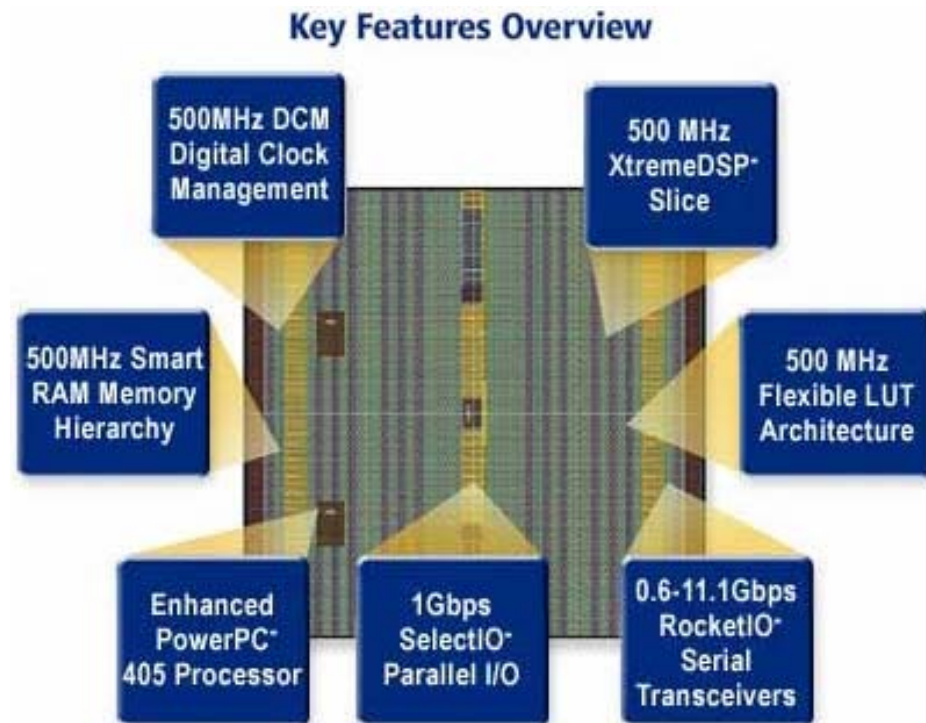
# Project timeline

- BEE2 PCB layout design (9/2004, done)
- PCB fabrication of 2 prototype boards (12/2004, done)
- 2 compute nodes testing and characterization (1/2005)
- 10 node system manufacturing (4/2005)
- Demonstration applications:
  - SETI billion channel spectrometer (6/2005)
  - 32 antenna 500MHz dual polarization correlator (12/2005)
  - Wide-field imager (12/2005)



# Future: BEE3 in sight!

- Xilinx just announced Virtex-4 family
  - 4~6X performance improvement
- DDR2 Memory specification up to 800MHz, 4GB per DIMM
- 100 Gbps Infiniband specification under development
- Direct scaling of BEE2 architecture
- Implementation possible in 1 years





# Staged Development of Peta-BEE

machine	BEE2 prototype	BEE2 full-rack	BEE3 full-rack	BEE4 prototype	BEE4 full-rack
year	Q1 2005	Q3 2005	Q1 2006	Q1 2007	Q3 2007
chip technology	130 nm	130 nm	90 nm	65 nm	65nm
fixed-point perf.	1.6-2 TOPS	32-40 TOPS	128-160 TOPS		<b>2048-2560 TOPS</b>
FP performance	64-80 GFLOPS	1.3-1.6 TFLOPS	5.12-6.4 TFLOPS		82-122 TFLOPS
with acceleration					(400-600 TFLOPS)
special				custom masks	custom masks
				stacked-die	stacked-die

- **Notes:**

- “prototypes” are 2 modules.
- “full-rack” versions are 40 modules, plus necessary switches, power supplies, etc.
- BEE3 implementation is optional.
- Schedule reflects technical feasibility. Development schedule would build in slack.

- **BEE4:**

- Assumes 65nm by late 2006.
- Special masks may be needed to provide proper balance of I/O, memory, and logic.
- Special masks could boost floating point performance (5x) if needed by applications.
- Memory die stacked on FPGAs to gain 4x in density.



# The BEE2 Team

- Faculty in charge
  - *John Wawrzynek*
  - *Bob W. Brodersen*
- Graduate students
  - *Chen Chang*
  - *Pierre-Yves Droz*
  - *Nan Zhou*
  - *Yury Markovskiy*
  - *Zohair Hyder*
  - *Adam Megacz*
  - *Alexander Krasnov*
  - *Hayden So*
  - *Kevin Camera*
- Industrial Liaison
  - *Bob Conn (Xilinx)*
  - *Ivo Bolsens (Xilinx)*
- Research associates
  - *Dan Werthimer (SSL)*
  - *Melvyn Wright (UCB, RAL)*
  - *Don Backer (UCB, astro)*
- Technical staff
  - *Brian Richards*
  - *Susan H. Mellers*
- Undergraduate student
  - *Greg Gibeling*